

1 **ABSTRACT**

2 Semiconductor devices and methods of forming semiconductor devices are
3 described. In one embodiment, a method comprises forming at least one
4 conductive structure within a plurality of semiconductor substrates, said act of
5 forming comprising first forming said at least one conductive structure to extend
6 into a respective semiconductor substrate a distance that is less than an elevational
7 thickness of the substrate, and second removing substrate material elevationally
8 adjacent said one conductive structure effective to expose a surface of said one
9 conductive structure, at least portions of one of the conductive structures having
10 oppositely facing, exposed outer surfaces; and stacking individual substrates
11 together such that individual conductive structures on each substrate are in
12 electrical contact with the conductive structures on a next adjacent substrate.

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